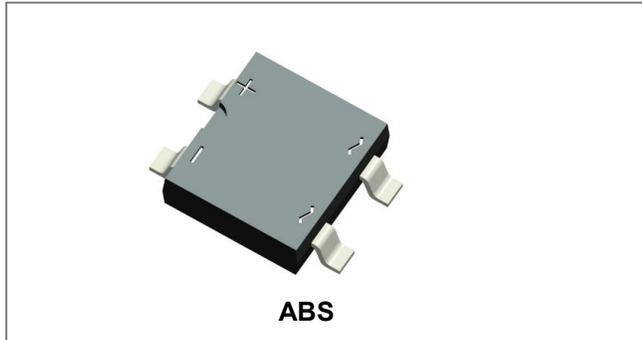


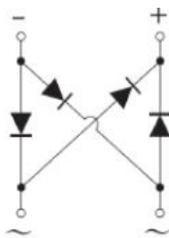
EABS21 THRU EABS26
SINGLE PHASE 2AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER



Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SOPA-4, Molded plastic ABS
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Weight: 0.101 grams(approx)
-

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Type Number	Symbol	EABS21	EABS22	EABS24	EABS26	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	100	200	400	600	V
RMS Reverse Voltage	V_{RMS}	70	140	280	420	V
Average Rectified Output Current @T _C =100°C	$I_{(AV)}$	2.0				V
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60				A
Rating for fusing (t<8.3ms)	I^2t	14.94				A ² s

Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	EABS21	EABS22	EABS24	EABS26	Units
Maximum Forward Voltage (per element) @ $I_F=2\text{A}$	V_F	0.95		1.25	1.70	V
Maximum Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_R	5.0 500				μA
Maximum Reverse Recovery Time (Note 1)	T_{rr}	35				ns

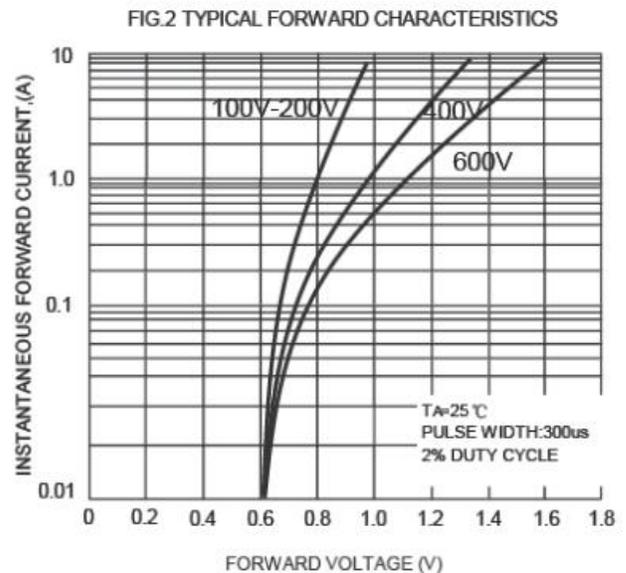
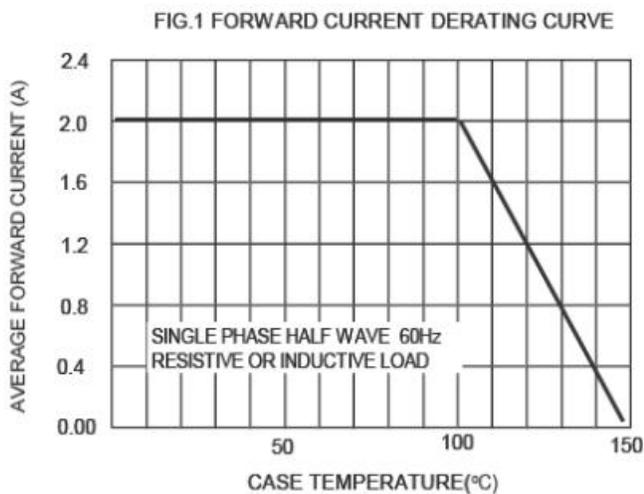
* Pulse width < 300 μs , duty cycle < 2%

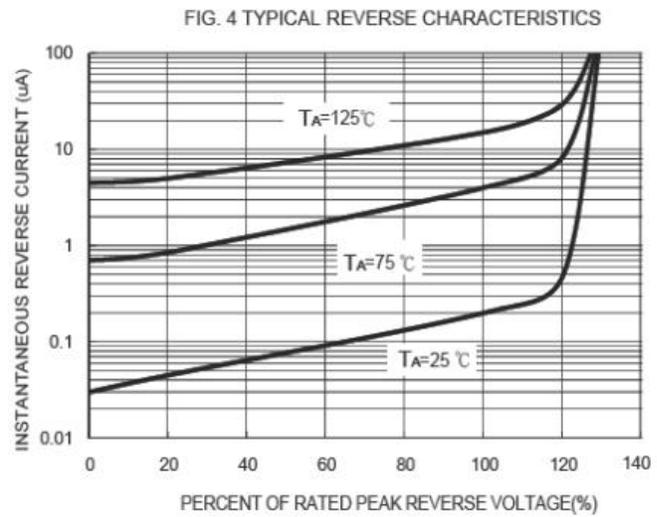
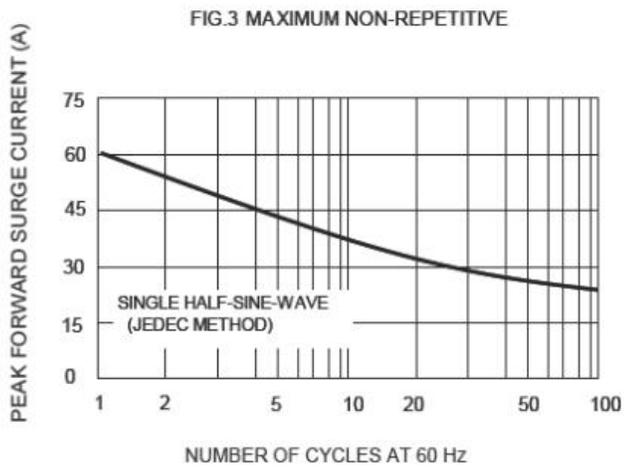
Thermal-Mechanical Specifications @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	EABS21	EABS22	EABS24	EABS26	Units
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	62.5 25				$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150				$^\circ\text{C}$

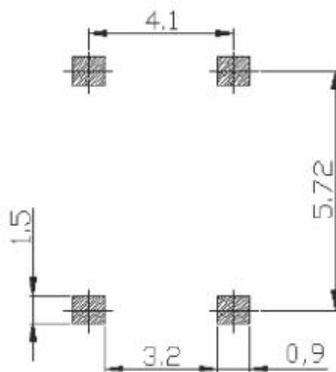
Note:1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Ratings and Characteristics Curves





ABS PAD LAYOUT

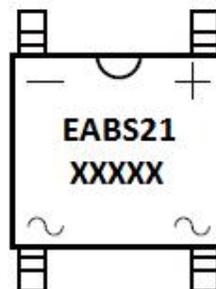


Ordering Information

Device	Package	Plating	Shipping
EABS21 THRU EABS26	ABS (Pb-Free)	Pure Sn	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

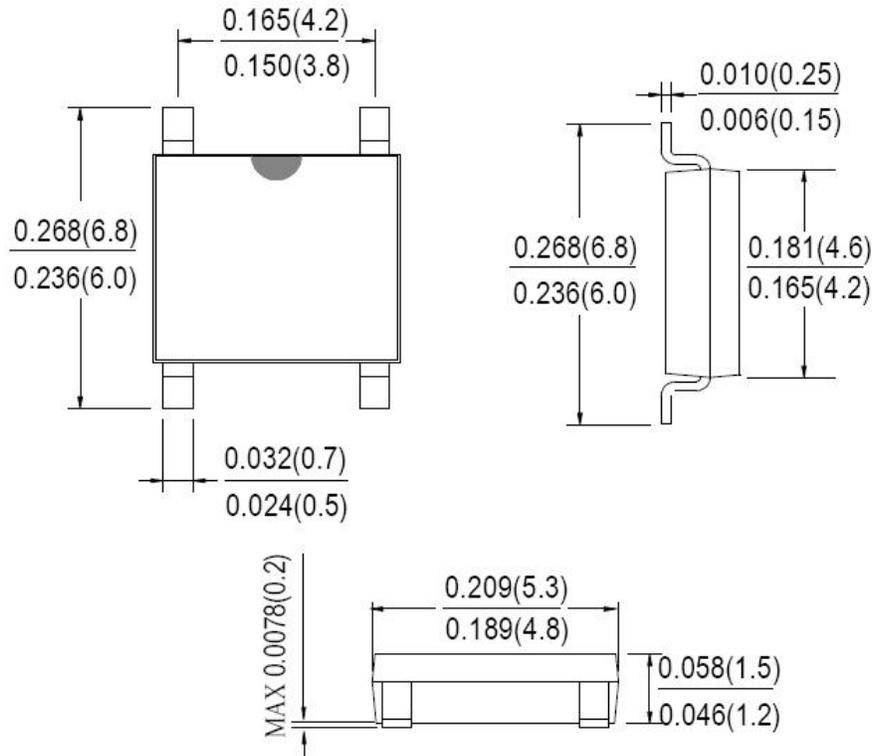


Where XXXXX is YYWWL

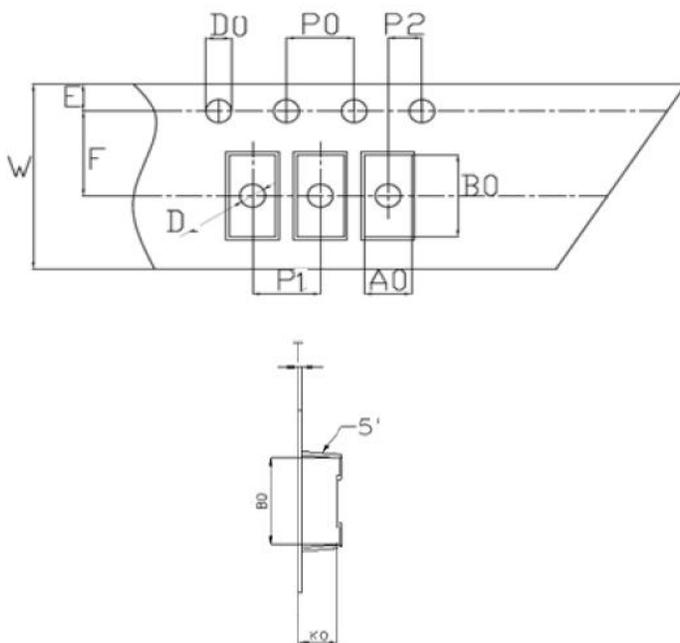
EABS21 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Mechanical Dimensions ABS(Inches/Millimeters)



Carrier Tape Specification ABS



SYMBOL	Millimeters	
	Min.	Max.
A0	5.21	5.41
B0	7.10	7.30
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	1.55	1.75
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20

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